

5

THIS SHEET HAS BEEN
REPLACED

ABSTRACT

Integrated circuits such as transponders (10) are attached to a substrate (28) such as cardboard packaging material by adhering an integrated circuit to the substrate, applying a patch antenna (18) to the substrate and the integrated circuit, and applying a sealing layer (40) over the integrated circuit and at least a portion of the antenna. In variations of the method, an indentation (34) may be formed in the substrate into which the integrated circuit is placed. The patch antenna may be screen printed onto the substrate and the integrated circuit, using conductive ink, or may be a metallic foil which is applied to the substrate and the integrated circuit. Where the integrated circuit is a transponder, it can be programmed with an identification code, either before or after being attached to the substrate.

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